# MSKSEMI















**ESD** 

TVS

TSS

MOV

**GDT** 

**PLED** 

# Brodnet data speet

www.msksemi.com









- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Extremely small surface mounting type.(DFN0603)
- Low IR.
- High reliability.

#### **APPLICATIONS**

• Low current rectification

0201

# **MAXIMUM RATINGS(Ta = 25°C)**

Parameter	Symbol	Limits	Unit
DC Reverse Voltage	VR	30	V
Mean Rectifying Current	10	100	mA
Peak Forward Surge Current	IFSM	2	Α

#### **THERMAL CHARACTERISTICS**

Parameter	Symbol	Limits	Unit
Total Device Dissipation,	PD		
FR-5 Board (Note 1) @ TA = 25°C		200	mW
Derate above 25°C		1.58	mW/ºC
Thermal Resistance,	RΘJA	500	°C/W
Junction-to-Ambient(Note 1)			
Junction Temperature	TJ	125	°C
Storage Temperature Range	Tstg	<b>−40~+150</b>	°C
Operating Temperature Range	Тор	<b>−40~+125</b>	°C

<sup>1.</sup>  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.

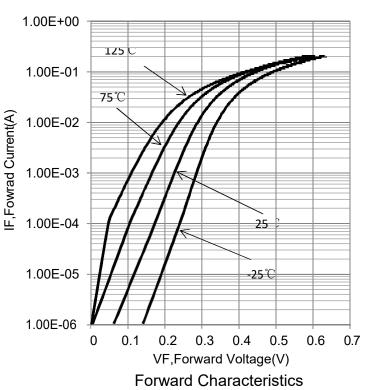
### **ELECTRICAL CHARACTERISTICS (Ta= 25°C)**

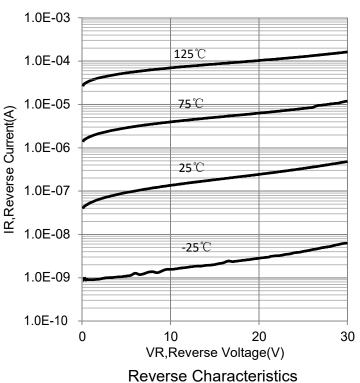
Characteristic	Symbol	Min.	Тур.	Max.	Unit
Reverse Voltage Leakage Current	IR				μA
(VR = 10Vdc)		-	-	0.35	
(VR = 30Vdc)		-	-	0.7	
Diode Capacitance	СТ				pF
(VR = 0V , f = 1.0 MHz)		-	8.2	-	
Forward Voltage	VF				V
(IF = 100 mAdc)		-	-	0.62	
(IF = 10 mAdc)		-	-	0.5	

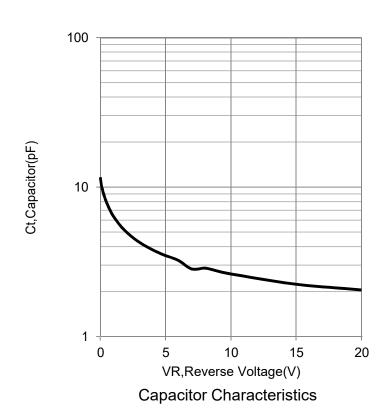


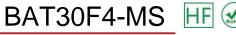


#### **ELECTRICAL CHARACTERISTICS CURVES**





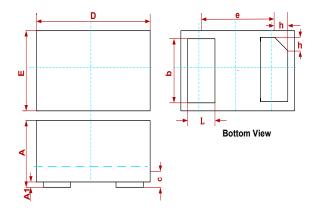






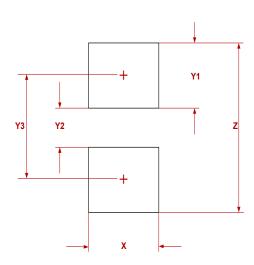


## **PACKAGE MECHANICAL DATA**



	DIMENSIONS			
	MILLIMETERS			
SYM	MIN	NOM		MAX
Α	0.230		(	0.330
A1	0.000	0.020	(	0.050
b	0.215	0.245	(	).275
С	0.120	0.150	(	0.180
D	0.550	0.600	(	0.650
е	0.355 BSC			
Е	0.250	0.300		0.350
L	0.160	0.190		0.220
h	0.079 BSC			

# **Suggested Pad Layout**



SYM	DIMENSIONS		
STIVI	MILLIMETERS	INCHES	
Х	0.30	0.012	
Y1	0.25	0.010	
Y2	0.15	0.006	
Y3	0.40	0.016	
Z	0.65	0.026	

### **REEL SPECIFICATION**

P/N	PKG	QTY
BAT30F4-MS	0201	10000

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